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Dated: August 23, 2005

Signature: Jean Bove

Jean Bove

Ref.: 7452-105/10313554
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Shih-Ping Hsu

Confirmation No.: 6002

Application No.: 10/695,356

Group Art Unit: 2813

Filed: October 27, 2003

Examiner: Nema O. Berezny

For: SEMICONDUCTOR PACKAGE
SUBSTRATE HAVING CONTACT PAD
PROTECTIVE LAYER FORMED THEREON
AND METHOD FOR FABRICATING THE
SAME

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
Mail Stop: AF

Dear Sir:

In response to the Office Action mailed April 12, 2005, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.